Qualcomm

Qualcomm Technologies, Inc.

PCN 4714A All Products

Process Change Notification
80-27429-1 Rev. B
4/21/2021

Process Change Notification

	PCN Tracking #: 4714A
Issue Date: 4/1/21 (Revised: 4/21/21)	**Effective Date**: 10/1/21

Reason for Revision:
To update the 'Assembled In' location removal.

Type of Change:
Extension of product shelf life and labeling change.

Description of Changes:
- QCT will extend the product minimum shelf life from 30 months to 42 months for MSL 2-5a products.
- The 1D barcode and seal date will be removed from the T&R and Tray labels.
- The MSD Caution label will have the updated bake instruction and include the bag seal date.

Reason for Change:
- QCT performed detailed analysis and determined 42 months to be the acceptable period for shelf-life expectancy for MSL 2-5a products stored at < 40°C and < 90% RH.
- Removal of 1D barcode is to increase the font size of the human readable characters for better readability.
- Changes to the MSD caution label is to conform with the current QCT's product requirements and to align with IPC/JEDEC J-STD-033 standard.

Affected Product List:
All Products

Data to Justify Change:
Not applicable

Suggested Implementation Plan:
QCT will cut over to the 42-month shelf life, and new labels at packing operation from the effective date. There will be a time period where customers will receive both versions as we transition our label inventory from one version to the other.

Impact on Form, Fit & Function:
The packing labels will change.

Impact on Software:
Not applicable

Affected Product documentation:
80-VK055-1 IC Products Packing Method

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New Parts will by Identified by:

The new labels will be as follows:

1. MSD Label

CAUTION
MOISTURE-SENSITIVE DEVICES

1. Devices must be handled and stored per IPC/JEDEC J-STD-033

2. Calculated shelf life in sealed bag: 42 months at < 40 C° and < 90% RH

3. Devices require bake before mounting if:
   a) Humidity Indicator Card reads >10% for level 2a - 5a devices or >60% for level 2 devices when read at 23±5 C°   OR
   b) "Factory floor life" is met or exceeded

4. If baking is required, bake devices at 125 +10/-0° C
   a) for packages ≤1.4mm thickness bake for 12 hours
   b) for packages >1.4mm thickness follow IPC/JEDEC J-STD-033
   (Do not bake in tape and reel)

5. See product device specification for PCB mounting guidelines

Note: Level and body temperature defined by IPC/JEDEC J-STD-020

Sealed Date:

2. Intermediate Box Label for Tape & Reel shipments

QUALCOMM		(1J) LPN: UN144356508 RTK00NYN	(Q) Quantity: 4000
		(1T) Lot Code: 000JE0308HS8E0307RN80E00188888	(9D) D/C: 20302030A
		(1P) Item ID: MSM-8994-N-1044SNSP-TR-00-0	MSL: 3 2nd L.I.: (e1) Assembled in: Taiwan

3. MBB (moisture barrier bag) and Reel label for Tape & Reel shipments

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(1J) LPN: UN144356508 **RTK00NYN**   (Q) Quantity: **4000**

(1T) Lot Code: **000JE0308HS8E0307RN80E00188888**   (9D) D/C: 20302030A

MSL: 3   2nd L.I.: (e1)

(1P) Item ID: MSM-8994-N-1044SNSP-TR-00-0

4. Intermediate Box Label for Tray shipments

QUALCOMM

(1J) LPN: UN144356508 **RTK00NYN**   (Q) Quantity: **4000**

(1T) Lot Code: **000JE0308HS-E0307RN.0E001**

(1P) Item ID: MSM-8994-N-1044SNSP-TR-00-0   (9D) D/C: 20302030A

MSL: 3   2nd L.I.: (e1)

Assembled in: S. Korea

5. MBB (moisture barrier bag) label for tray shipments

QUALCOMM

(1J) LPN: UN144356508 **RTK00NYN**   (Q) Quantity: **4000**

(1T) Lot Code: **000JE0308HS-E0307RN.0E001**

(1P) Item ID: MSM-8994-N-1044SNSP-TR-00-0   (9D) D/C: 20302030A

MSL: 3   2nd L.I.: (e1)

Changed material may be shipped as of the effective date specified above.
For questions and information, please contact customer service at your branch office.
For questions after the effective date of this PCN, please reference product documentation for latest updates or requirements at https://support.cdmatech.com/login/